What is claimed is:

SUB B1

1. A multilayer circuit board comprising:

a substrate having a first surface and a second surface extending from an end of the first surface at a required angle relative to the first surface;

a multilayer circuit formed on the first surface of said substrate and composed of a plurality of circuit layers, each of which is provided with a conductive layer having a required circuit pattern and an insulation layer formed on said conductive layer by film formation;

a second conductive layer formed on the second surface of said substrate, by which a layer-to-layer connection of said multilayer circuit is made.

2. The multilayer circuit board as set forth in claim 1, wherein the second surface of said substrate is a side surface of a projection on the first surface.

3. The multilayer circuit board as set forth in claim 1, wherein the first surface is a top surface of said substrate, and the second surface is a side surface of said substrate.

4. The multilayer circuit board as set forth in claim 1, wherein the required angle between the first and second surfaces is an obtuse angle.

5. The multilayer circuit board as set forth in claim 1, wherein said multilayer circuit has an aperture, through which a part of the first surface is exposed, and an electronic device is mounted in a concave formed in the exposed first surface, and an electrical connection between said multilayer circuit and said electronic device is made by a third conductive layer formed on an inner surface of said concave.

6. The multilayer circuit board as set forth in claim 1, wherein said second conductive layer is a plurality of second conductive layers to obtain plural layer-to-layer connections of said multilayer circuit, and each of second conductive layers is separated from an adjacent second conductive layer in the thickness direction by a second insulation layer.

7. The multilayer circuit board as set forth in claim 1, wherein said substrate has a third surface extending at a different level from the first surface and a fourth surface extending from the other end of the first surface to an end of the third surface, and said multilayer circuit is formed on the first, third and fourth surfaces of said substrate, and said second conductive layer is formed on a side surface of a projection on the first surface to make the layer-to-layer connection of said multilayer circuit.

8. A method of manufacturing a multilayer circuit board comprising the steps

of:

providing a substrate having a first surface and a second surface extending from an end of the first surface at a required angle relative to the first surface;

performing a given number of circuit-layer forming steps to obtain a multilayer circuit on the first surface of said substrate, each of said circuit-layer forming steps including forming a conductive layer having a required pattern and forming an insulation layer on said conductive layer by means of film formation;

forming a second conductive layer on the second surface of said substrate, by which a layer-to-layer connection of said multilayer circuit is made.

9. The method as set forth in claim 8, wherein the first surface is a top surface of said substrate, and the second surface is a side surface of a projection on the first surface, and wherein said second conductive layer is formed on the side surface of said projection during said circuit-layer forming steps.

10. The method as set forth in claim 8, wherein said second conductive layer is obtained by cutting said substrate having said multilayer circuit such that a cutting surface of said multilayer circuit is flush with the cutting surface of said substrate, and forming a conductive film for layer-to-layer connection on the cutting surfaces of said multilayer circuit and said substrate.

11. The method as set forth in claim 8, wherein said second conductive layer is obtained by forming a copper film on said second surface, and removing a required region of said copper film by use of a laser beam.

12. The method as set forth in claim 8, wherein the first surface is a top surface of said substrate, and the second surface is a side surface of said substrate, and wherein said second conductive layer is formed on the side surface.

13. The method as set forth in claim 8, wherein said insulation layer is formed by means of one of deposition polymerization and plasma polymerization.

14. The method as set forth in claim 8, wherein said insulation layer is obtained by forming a film of an insulating resin having photocurability, and curing said film under light irradiation.

15. The method as set forth in claim 8, wherein said insulation layer is obtained by thermo-compression bonding a sheet of an insulating resin on

said conductive layer.